



**THE DATASHEET OF  
CSD10060G**



# CSD10060–silicon Carbide Schottky Diode

## ZERO RECOVERY<sup>®</sup> RECTIFIER

$V_{RRM} = 600\text{ V}$   
 $I_{F(AVG)} = 10\text{ A}$   
 $Q_c = 28\text{ nC}$

### Features

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on  $V_F$

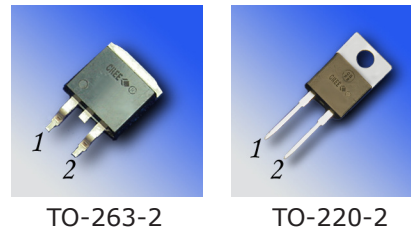
### Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

### Applications

- Switch Mode Power Supplies
- Power Factor Correction
  - Typical PFC  $P_{out}$  : 1000W-2000W
- Motor Drives
  - Typical Power : 3HP-5HP

### Package



Part Number	Package	Marking
CSD10060A	TO-220-2	CSD10060
CSD10060G	TO-263-2	CSD10060

### Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	600	V		
$V_{RSM}$	Surge Peak Reverse Voltage	600	V		
$V_{DC}$	DC Blocking Voltage	600	V		
$I_{F(AVG)}$	Average Forward Current	10 16.5	A	$T_C=150^\circ\text{C}$ $T_C=125^\circ\text{C}$	
$I_{F(Peak)}$	Peak Forward Current	23	A	$T_C=125^\circ\text{C}$ , $T_{REP}<1\text{ mS}$ , Duty=0.5	
$I_{FRM}$	Repetitive Peak Forward Surge Current	43 29	A	$T_C=25^\circ\text{C}$ , $t_p=10\text{ ms}$ , Half Sine Wave $T_C=125^\circ\text{C}$ , $t_p=10\text{ ms}$ , Half Sine Wave	
$I_{FSM}$	Non-Repetitive Peak Forward Surge Current	77	A	$T_C=25^\circ\text{C}$ , $t_p=1.5\text{ ms}$ , Half Sine Wave	
$I_{FSM}$	Non-Repetitive Peak Forward Surge Current	250	A	$T_C=25^\circ\text{C}$ , $t_p=10\text{ }\mu\text{s}$ , Pulse	
$P_{tot}$	Power Dissipation	136.3 45.4	W	$T_C=25^\circ\text{C}$ $T_C=125^\circ\text{C}$	
$T_j$ , $T_{stg}$	Operating Junction and Storage Temperature	-55 to +175	$^\circ\text{C}$		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	

## Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_F$	Forward Voltage	1.5 2.0	1.8 2.4	V	$I_F = 10\text{ A}$ $T_J = 25^\circ\text{C}$ $I_F = 10\text{ A}$ $T_J = 175^\circ\text{C}$	
$I_R$	Reverse Current	50 100	200 1000	$\mu\text{A}$	$V_R = 600\text{ V}$ $T_J = 25^\circ\text{C}$ $V_R = 600\text{ V}$ $T_J = 150^\circ\text{C}$	
$Q_C$	Total Capacitive Charge	28		nC	$V_R = 600\text{ V}$ , $I_F = 10\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$	
C	Total Capacitance	550 65 50		pF	$V_R = 0\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ $V_R = 200\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ $V_R = 400\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$	

Note:

1. This is a majority carrier diode, so there is no reverse recovery charge.

## Thermal Characteristics

Symbol	Parameter	Typ.	Unit
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.1	$^\circ\text{C}/\text{W}$

## Typical Performance

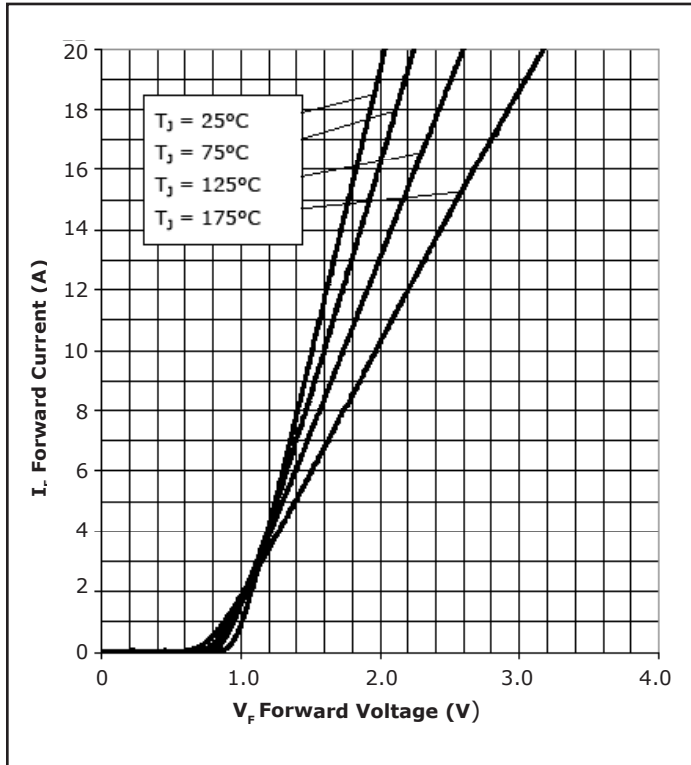


Figure 1. Forward Characteristics

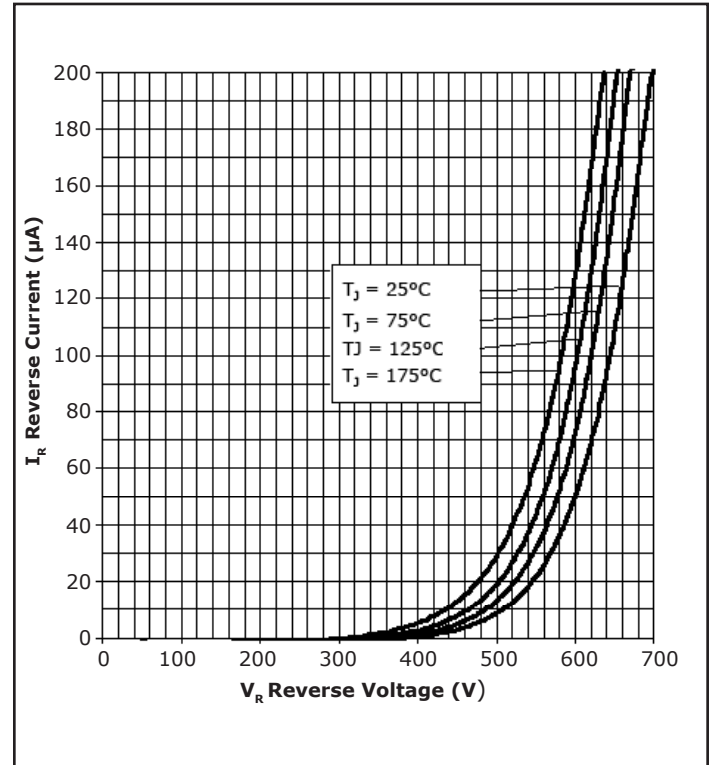


Figure 2. Reverse Characteristics

# Typical Performance

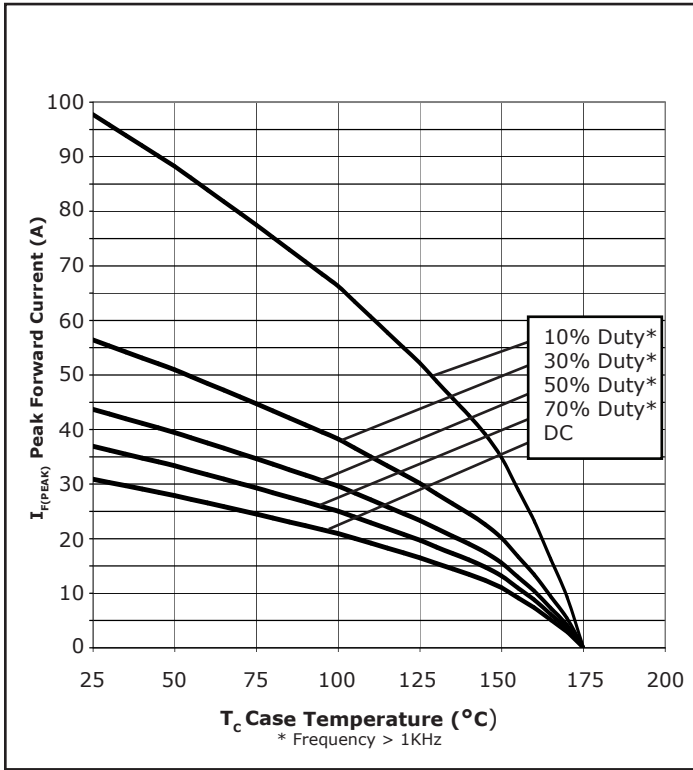


Figure 3. Current Derating

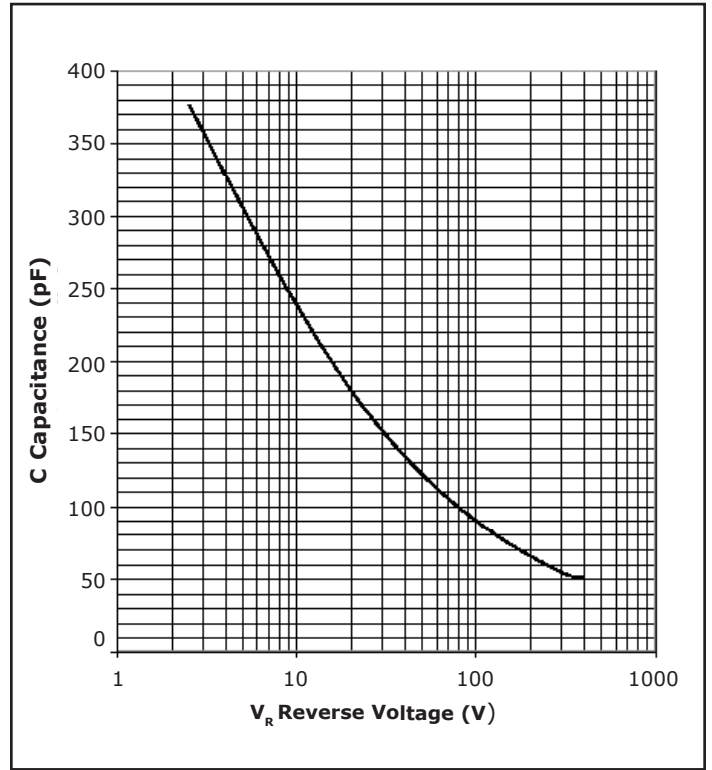


Figure 4. Capacitance vs. Reverse Voltage

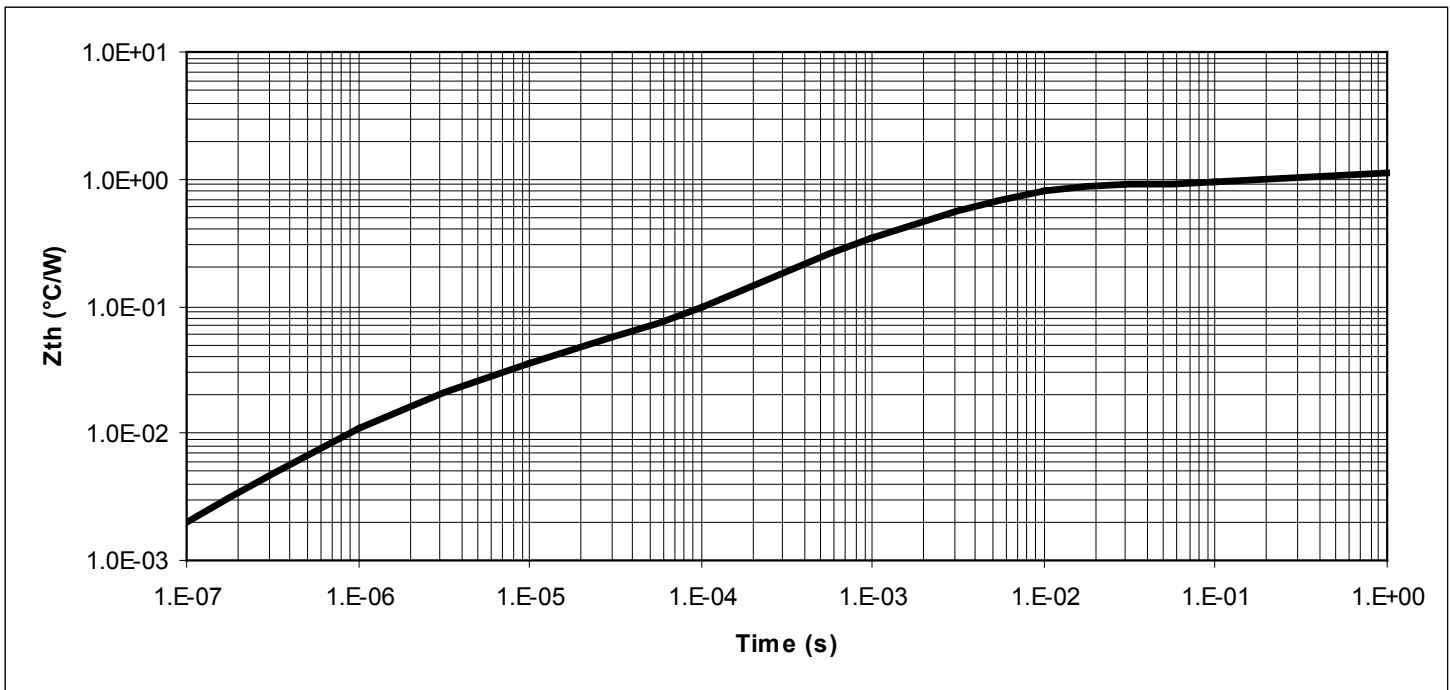


Figure 5. Transient Thermal Impedance

# Typical Performance

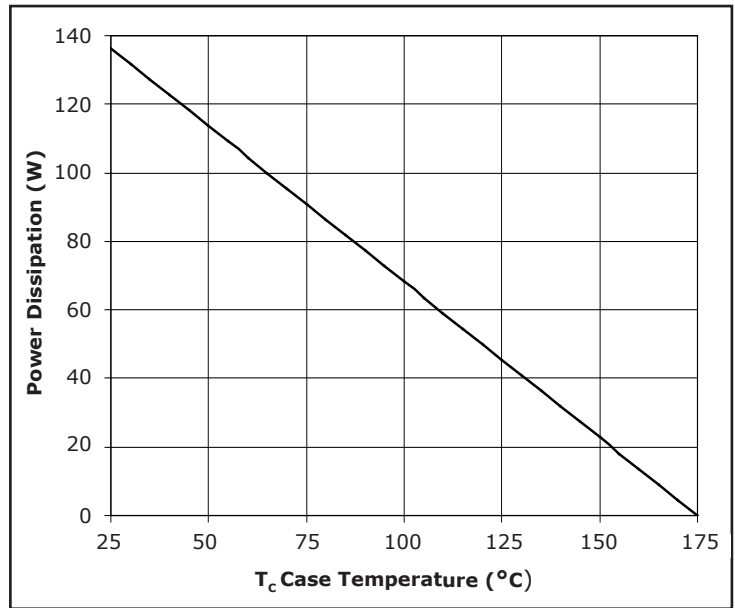
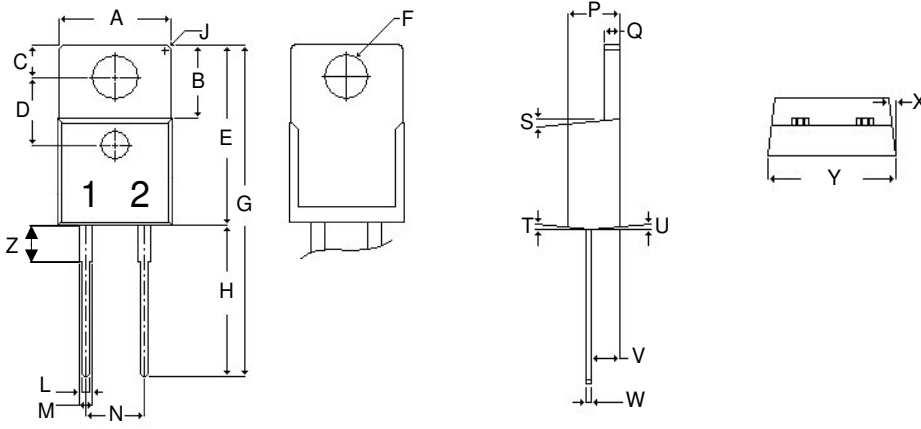


Figure 6. Power Derating

## Package Dimensions

Package TO-220-2



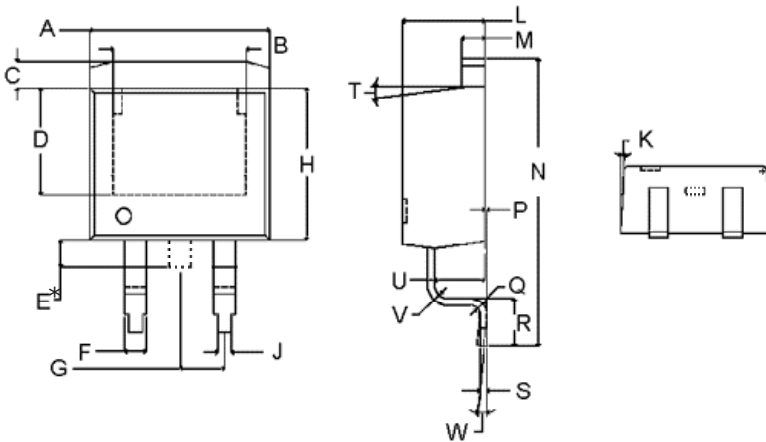
POS	Inches		Millimeters	
	Min	Max	Min	Max
A	.381	.410	9.677	10.414
B	.235	.255	5.969	6.477
C	.100	.120	2.540	3.048
D	.223	.337	5.664	8.560
E	.590	.615	14.986	15.621
F	.143	.153	3.632	3.886
G	1.105	1.147	28.067	29.134
H	.500	.550	12.700	13.970
J	R 0.197		R 0.197	
L	.025	.036	.635	.914
M	.045	.055	1.143	1.397
N	.195	.205	4.953	5.207
P	.165	.185	4.191	4.699
Q	.048	.054	1.219	1.372
S	3°	6°	3°	6°
T	3°	6°	3°	6°
U	3°	6°	3°	6°
V	.094	.110	2.388	2.794
W	.014	.025	.356	.635
X	3°	5.5°	3°	5.5°
Y	.385	.410	9.779	10.414
Z	.130	.150	3.302	3.810

NOTE:

1. Dimension L, M, W apply for Solder Dip Finish

## Package Dimensions

Package TO-263-2

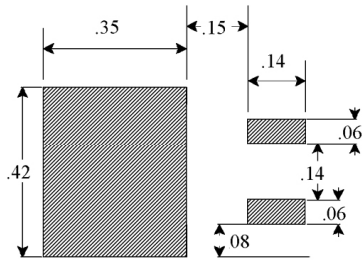


POS	Inches		Millimeters	
	Min	Max	Min	Max
A	.396	.406	10.058	10.312
B	.297	.303	7.544	7.696
C	.057	.063	1.448	1.600
D	.237	.243	6.015	6.167
E*	0.00	.070	0.00	1.778
F	.048	.062	1.219	1.575
G	.100 TYP		2.540 TYP	
H	.335	.345	8.509	8.763
J	.028	.034	.711	.864
K	2°	4°	2°	4°
L	.170	.180	4.318	4.572
M	.048	.052	1.219	1.321
N	.595	.615	15.113	15.621
P	0.00	0.10	0.00	.254
Q	R0.018 TYP	R0.022 TYP	R0.457 TYP	R0.559 TYP
R	.090	.110	2.286	2.794
S	.013	.017	.330	.432
T	6.5°	8.5°	6.5°	8.5°
U	.103	.107	2.616	2.718
V	R0.028 TYP	R0.032 TYP	R0.711 TYP	R0.813 TYP
W	—	5.0°	—	5.0°

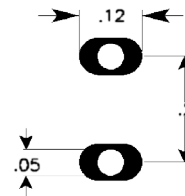
Note:

- \* Tab "E" may not be present

## Recommended Solder Pad Layout



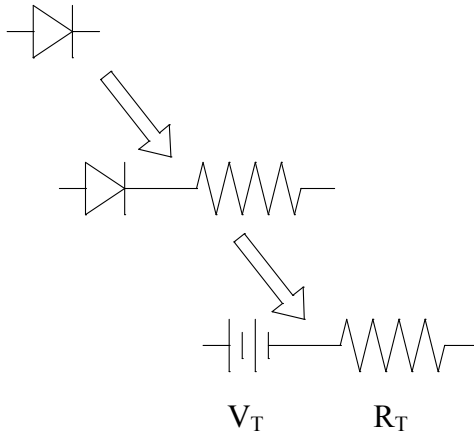
TO-263-2



TO-220-2

Part Number	Package	Marking
CSD10060A	TO-220-2	CSD10060
CSD10060G	TO-263-2	CSD10060

## Diode Model



$$V_{fT} = V_T + I_f * R_T$$

$$V_T = 0.92 + (T_j * -1.35 * 10^{-3})$$

$$R_T = 0.052 + (T_j * 0.29 * 10^{-3})$$

**Note:**  $T_j$  = Diode Junction Temperature In Degrees Celcius

"The levels of environmentally sensitive, persistent biologically toxic (PBT), persistent organic pollutants (POP), or otherwise restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS), as amended through April 21, 2006. This part number was released previously with Sn/Pb solder plating as a standard industry finish. For more information please contact [power\\_sales@cree.com](mailto:power_sales@cree.com)"

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